

© Liquid crystal panel manufacturing jig: high temperature rigidity



**High temperature stiffness (300 ° C or More)**

**【Conventional material】**

Metal, other thermoplastic materials (PEEK), Non-Thermoplastic PI

**【Issues of conventional materials】**

Metal: Metal dust (contamination of the liquid crystal panel)

Resin: High temperature stiffness (300 ° C or More),  
low cost (injection molding)

**【Required characteristic】**

Liquid crystal panel contamination,  
High temperature rigidity (300 ° C or More)

**AURUM™ Advantage**

- High temperature stiffness (300 ° C or More)
- low dust emission
- Low cost (injection molding)

**Injection molding for use in high temperature environments  
(300 ° C or More)**



Recommended grade : JCN6230 (crystallization needed)